

Terrace 1		Corrosion Reliability of Electronic Materials and Devices
	<i>Chair(s)</i>	<i>H. Schweigart / M. Jellesen</i>
11:10	80371	Sabine Knapke (Robert Bosch GmbH, Reutlingen, Germany) / Katharina Schultz (Robert Bosch GmbH, Reutlingen, Germany) / Klaus Micheler (Robert Bosch GmbH, Reutlingen, Germany): Electrochemical Corrosion and Thermal Effects in Electronic Systems
11:30	79211	Elke Ludwig (TU Wien, Wien, Austria) / Paul Linhardt (TU Wien, Vienna, Austria) / Maximilian Bonta (TU Wien, Vienna, Austria) / Andreas Limbeck (TU Wien, Vienna, Austria) / Johannes Frank (TU Wien, Vienna, Austria) / Silvia Larissegger (KAI, Villach, Austria) / Michael Nelhiebel (KAI, Villach, Austria): Corrosion of Copper in Combination with Polyimide
11:50	98145	Kamila Piotrowska (Technical University of Denmark, Lyngby, Denmark) / Morten Stendahl Jellesen (Technical University of Denmark, Lyngby, Denmark) / Rajan Ambat (Technical University of Denmark, Lyngby, Denmark): The influence of solder mask and hygroscopic flux residues on water layer formation on PCBA surface and corrosion reliability of electronics
12:10	96852	Jesper Konge (Grundfos A/S, Bjerringbro, Denmark): A strategic approach to Electronics Corrosion Reliability
12:30		Lunch
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	<i>Chair(s)</i>	<i>M. Bálint / R. Ambat</i>
14:00	80611	Sabine Reither (Kompetenzzentrum Automobil- und Industrieelektronik GmbH, Villach, Austria) / Maximilian Bonta (Kompetenzzentrum Automobil- und Industrieelektronik GmbH, Villach, Austria) / Silvia Larissegger (Kompetenzzentrum Automobil- und Industrieelektronik GmbH, Villach, Austria) / Michael Nelhiebel (Kompetenzzentrum Automobil- und Industrieelektronik GmbH, Villach, Austria) / Andreas Limbeck (TU Wien, Wien, Austria) / Günter Fafilek (TU Wien, Wien, Austria): Electrochemical characterization of copper films and comparison of strategies for corrosion protection
14:20	87386	Helmut Schweigart (Dr. O.K. Wack Chemie GmbH, Ingolstadt, Donau, Germany): Fast and Cost-Effective Coating Quality Test
14:40	83451	Vadimas Verdingovas (Technical University of Denmark, Kgs. Lyngby, Denmark) / Morten Jellesen (Technical University of Denmark, Kgs. Lyngby, Denmark) / Rajan Ambat (Technical University of Denmark, Kgs. Lyngby, Denmark): Critical level of water layer formation on PCBA and sequential failure
15:00	81676	Bálint Medgyes (Budapest University of Technology and Economics, Budapest, Hungary) / Gábor Harsányi (Budapest University of Technology and Economics, Budapest, Hungary) / László Gál (Budapest University of Technology and Economics, Budapest, Hungary): Electrochemical migration of Ni and ENIG surfaces finishes in different Na₂SO₄ solutions using THB Tests
15:20	79376	Aliakbar Khanghali (Vrije Universiteit Brussel, Belgium) / Tom Hauffman (Vrije Universiteit Brussel, Belgium) / Eva Rogge (Europlasma, Oudenaarde, Belgium) / Samir Loulidi (Europlasma, Oudenaarde, Belgium) / Iris De Graeve (Vrije Universiteit Brussel, Belgium): Study of plasma polymer films for the corrosion protection of Printed Circuit Boards
15:40		Coffee Break
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16:10	72626	Hiroyuki Abe (Hitachi Automotive Systems, Ltd., Ibaraki-ken, Japan) / Akio Yasukawa (Hitachi Automotive Systems, Ltd., Ibaraki-ken, Japan) / Rintaro Minamitani (Hitachi, Ltd., Research & Development Group, Ibaraki-ken, Japan) / Hiroyuki Saito (Tokyo Denki University, Tokyo, Japan): Corrosion life prediction of electronic module mounted in engine room by SO₂ gas released from rubber duct
16:30	73347	Tung Han Chuang (National Taiwan University, Taipei, Taiwan) / Yan Cheng Lin (National Taiwan University, Taipei, Taiwan) / Chun-Hao Chen (National Taiwan University, Taipei, Taiwan) / Chih-Hsin Tsai (Wire Technology Co., Taichung, Taiwan) / Shang-Chih Wang (Wire Technology Co., Taichung, Taiwan) / Hsing-Hua Tsai (Wire Technology Co., Taichung, Taiwan): Corrosion and Ion Migration of Ag-alloy Bonding Wires with various Pd and Au Contents
16:50	81251	Abhijeet Yadav (Technical University of Denmark, Lyngby, Denmark) / Visweswara Chakravarthy Gudla (Technical University of Denmark, Lyngby, Denmark) / Rajan Ambat (Technical University of Denmark, Lyngby, Denmark): Corrosion Reliability of Low Power Electrical Contacts
17:10	87216	Kirsten Weide-Zaage (Leibniz Universität Hannover, Hannover, Germany) / Helene Fremont (University of Bordeaux IMS laboratory UMR-5218, Bordeaux, France) / Alexandrine Guédon-Gracia (IMS laboratory UMR-5218, University of Bordeaux, Bordeaux, France) / Yuan Feng (RESRI Group, Leibniz Universität Hannover, Hannover, Germany) / Amin Chen (LUH IMS-RESRI, Hannover, Germany): Study of Corrosion in BGA Solder Balls
17:30		TF MEETING
19:00		Congress Dinner

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10:10	95962	Morten Stendahl Jellesen (Technical University of Denmark, Kongens Lyngby, Denmark) / Vadimas Verdingovas (DTU, Lyngby, Denmark) / Rajan Ambat (DTU, Lyngby, Denmark): Corrosion investigations of a voltage biased printed circuit board assembly under high humidity conditions
10:30	97435	Célia Aparecida Lino dos Santos (Laboratory for Corrosion and Protection, São Paulo, Brazil) / Zehbour Panossian (Laboratory for Corrosion and Protection, São Paulo, Brazil): The current stage of TR-Fe-B permanent magnet protection against corrosion
10:50	87396	Kim Albert Schmidt (FORCE Technology, Horsholm, Denmark) / Anders Bonde Kentved (FORCE Technology, Horsholm, Denmark): Method for practical characterization of humidity ingress in electronic enclosures
11:10	81106	Xiankang Zhong (Southwest Petroleum University, Chengdu, China): The role of precipitates in the electrochemical migration of Sn and Cu

Forum Hall Foyer		Corrosion Reliability of Electronic Materials and Devices
P-20-214	98957	Liao Bokai (Huazhong University of Science and Technology Wuhan, China PR) / Shuai Hu (Huazhong University of Science and Technology Wuhan, China PR) / Lisha Wei (Huazhong University of Science and Technology Wuhan, China PR) / Hongyu Cen (Huazhong University of Science and Technology Wuhan, China PR) / Zhenyu Chen (Huazhong University of Science and Technology Wuhan, China PR) / Xingpeng Guo (Huazhong University of Science and Technology Wuhan, China PR): Effect of solder flux residue weak organic acids on electrochemical migration of tin in thin electrolyte layer
P-20-215	98245	Feng Li (Technical University of Denmark, Lyngby, Denmark) / Vadimas Verdingovas (Technical University of Denmark, Lyngby, Denmark) / Bálint Medgyes (Budapest University of Technology and Economics, Budapest, Hungary) / Rajan Ambat (Technical University of Denmark, Lyngby, Denmark): Corrosion reliability of lead-free solder systems used in electronics
P-20-216	96797	Dusan Majtas (Masaryk University, Brno, Czech Republic) / Katerina Kreislova (SVUOM Ltd., Prague, Czech Republic) / Libor Turek (SVUOM Ltd., Prague, Czech Republic): Failure of electric devices due to H₂S
P-20-217	86311	Abhijeet Yadav (Technical University of Denmark, Lyngby, Denmark) / Shruti Bargaonkar (Technical University of Denmark, Lyngby, Denmark) / Kamila Piotrowska (Technical University of Denmark, Lyngby, Denmark) / Morten Stendahl Jellesen (Technical University of Denmark, Lyngby, Denmark) / Rajan Ambat (Technical University of Denmark, Lyngby, Denmark): The effect of reflow solder paste on corrosion reliability in electronics under humid conditions